TECHNICAL DATA SHEET

HOTMELT PRODUCT: APOLY500



Product Description

APOLY500 is a one component, solvent free, quick setting, moisture curing adhesive specially formulated for water resistant bonding. It can be used for the bonding of joinery, garden furniture, staircases, boats, sandwich panels and insulation materials. It offers excellent adhesion to hard and soft wood, chipboard, laminates, metals, expanded and extruded polystyrene foams, concrete, stone, bricks, gypsum boards and most traditional porous building substrates.

Application

Substrates to be bonded must be clean, dry and free from dust and grease. The ambient temperature of the substrates should be above 5°C and the moisture content less than 30%. Apply the adhesive to one surface of the substrates to be bonded at a rate of 120 to 250 g/m². Apply to both substrates if they are porous. If necessary, a light misting of water (approx. 30 g/m² is sufficient) will aid curing and enable the adhesive to expand slightly, thus filling any surface irregularities. Clamping the substrates together will improve the overall bond strength.

Curing

Curing time is 15 to 30 minutes, depending on the ambient temperature and moisture content etc. Full strength is normally achieved after 24 hours.

Technical Data

Colour: Brown
Density: 1.05 g/m³
Application temperature: 10 to 35°C

Usage: 120 to 150 g/m², depending on substrate

Temperature resistance: -30 to 120°C, once cured

Cleaning

Uncured adhesive can be removed using a Solvent Cleaner. Cured adhesive can only be removed mechanically, i.e. by scraping.

Storage and Shelf Life

APOLY500 should be stored at temperatures between 5°C and 25°C in the original unopened containers. Under these conditions the product should have a shelf life of 6 months.